

SOT905-1

plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3 x 3 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN24
Package type industry code	HVQFN24
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	24	-	

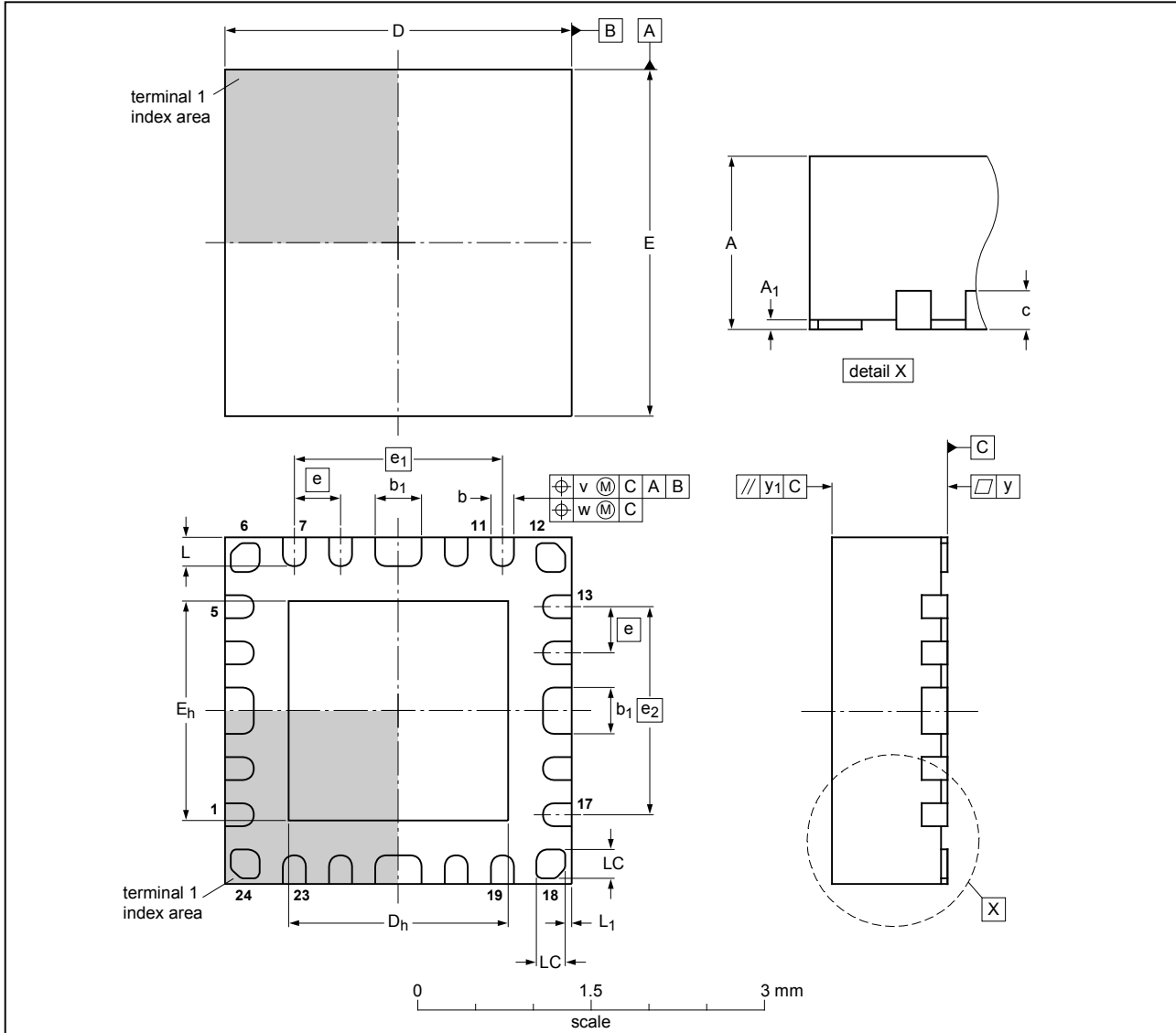


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2. Package outline

HVQFN24: plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3 x 3 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁	b	b ₁	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	L ₁	LC	v	w	y	y ₁
mm	1	0.05 0.00	0.25 0.15	0.45 0.35	0.2	3.1 2.9	2.05 1.75	3.1 2.9	2.05 1.75	0.4	1.8	1.8	0.35 0.15	0.1 0.0	0.3 0.2	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT905-1	---	---	---			06-03-13 06-03-31

Fig. 1. Package outline HVQFN24 (SOT905-1)

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3. Legal information

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